RELIABILITY REPORT

FOR

MAX6035BAUR50+

PLASTIC ENCAPSULATED DEVICES

August 23, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX6035BAUR50+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX6035 is a high-voltage, precision micropower voltage reference. This three-terminal device is available with output voltage options of 2.5V, 3.0V, and 5.0V. It is an excellent upgrade for industry-standard devices such as the REF02 and REF43. The MAX6035 offers 14x lower power than the REF02 and 5x lower power than the REF43, as well as a reduced package size from an 8-pin SO to a 3-pin SOT23. The MAX6035 features a proprietary temperature coefficient curvature-correction circuit and laser-trimmed, thin-film resistors that result in a very low temperature coefficient of 25ppm/°C (max) and an initial accuracy of ±0.2% (max). The MAX6035 typically draws only 73µA of supply current and can source 10mA or sink 2mA of load current. Unlike conventional shunt-mode (two-terminal) references that waste supply current and require an external resistor, this device offers a supply current that is virtually independent of the supply voltage and does not require an external resistor. Additionally, this internally compensated device does not require an external compensation capacitor, but is also stable with capacitive loads up to 5µF. Eliminating the external compensation capacitor saves valuable board area in space-critical applications. The supply independent, ultra-low supply current makes this device ideal for battery-operated, high-performance systems. The MAX6035 is available in a 3-pin SOT23 package and is specified for operation from -40°C to +125°C.

II. Manufacturing Information

A. Description/Function: High-Supply-Voltage, Precision Voltage Reference in SOT23
B. Process: HV3
C. Number of Device Transistors:
D. Fabrication Location: Oregon
E. Assembly Location: Malaysia, Thailand, Philippines
F. Date of Initial Production: October 25, 2002

III. Packaging Information

A. Package Type: 3-pin SOT23
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: 84-1lmisr4 Epoxy
E. Bondwire: Gold (1 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-0901-0194
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C: Level 1
J. Single Layer Theta Jb: 250*°C/W
K. Single Layer Theta Jc: 130°C/W

IV. Die Information

A. Dimensions: 44 X 31 mils
B. Passivation: Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect: Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization: None
E. Minimum Metal Width: Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing: Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO_2
I. Die Separation Method: Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 157 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.8 \times 10^{-9}$

λ = 6.8 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the HV3 Process results in a FIT Rate of 1.24 @ 25C and 21.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF35-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1

Reliability Evaluation Test Results

MAX6035BAUR50+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	157	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data